Materials Declaration

Package	TSSOP
Body Size	4.4
LeadCount	8
Option	Pb-Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Byphenyl resin	9	6.27 E-04	19129
SiO2 Filler	85	5.93 E-03	180665
Phenol Resin	5	3.49 E-04	10627
Antimony_Sb2O3	0.5	3.49 E-05	1063
Brominated Resin	0.5	3.49 E-05	1063

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	2.20 E-02	671117
Ni	3	6.87 E-04	20929
Si	0.65	1.49 E-04	4535
Mg	0.15	3.43 E-05	1046

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	3.00 E-04	9145

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	7.60 E-04	23169

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.57 E-04	4773

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	1.58 E-03	48166

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	3.75 E-05	1143
Ag Filler	75	1.13 E-04	3430

Molding Compound

Item	PPM	Method
Pb	Not Detected	ICP AES
Cd	Not Detected	ICP AES
Hg	Not Detected	ICP AES
Cr+6	Not Detected	DIN 53314

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

Package Totals

Weight (g)	PPM
3.28 E-02	1000000

AMK-RU-D

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc
any inaccuracy of such information.

Materials Declaration

Package	TSSOP
Body Size	4.4
LeadCount	8
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Byphenyl resin	9	6.27 E-04	19129
SiO2 Filler	85	5.93 E-03	180665
Phenol Resin	5	3.49 E-04	10627
Antimony_Sb2O3	0.5	3.49 E-05	1063
Brominated Resin	0.5	3.49 E-05	1063

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	2.20 E-02	671117
Ni	3	6.87 E-04	20929
Si	0.65	1.49 E-04	4535
Mg	0.15	3.43 E-05	1046

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	3.00 E-04	9145

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	6.46 E-04	19693
Pb	15	1.14 E-04	3.48 E+03

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.57 E-04	4773

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	1.58 E-03	48166

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	3.75 E-05	1143
Ag Filler	75	1.13 E-04	3430

Molding Compound

Item	PPM	Method
Pb	Not Detected	ICP AES
Cd	Not Detected	ICP AES
Hg	Not Detected	ICP AES
Cr+6	Not Detected	DIN 53314

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

Package Totals

Weight (g)	PPM
3.28 E-02	1000000

AMK-RU-A

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ANALOG DEVICES

ADI Proprietary

9/21/05